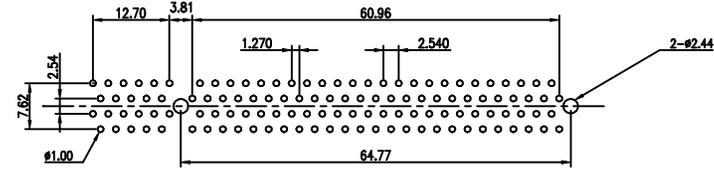
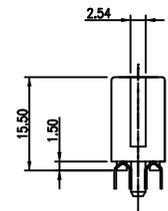
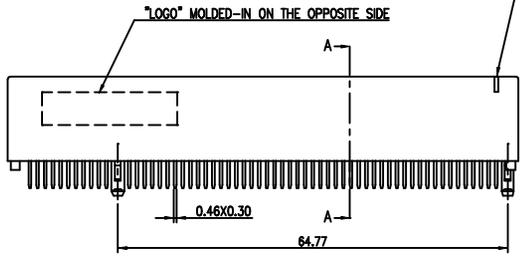
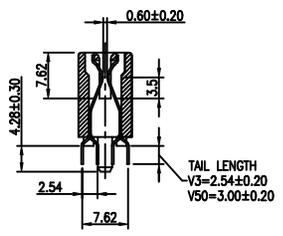
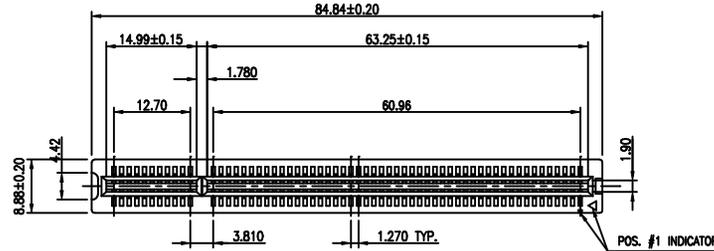


PART NUMBER
SEE SHEET 3



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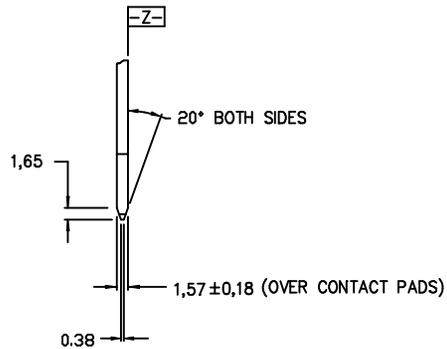
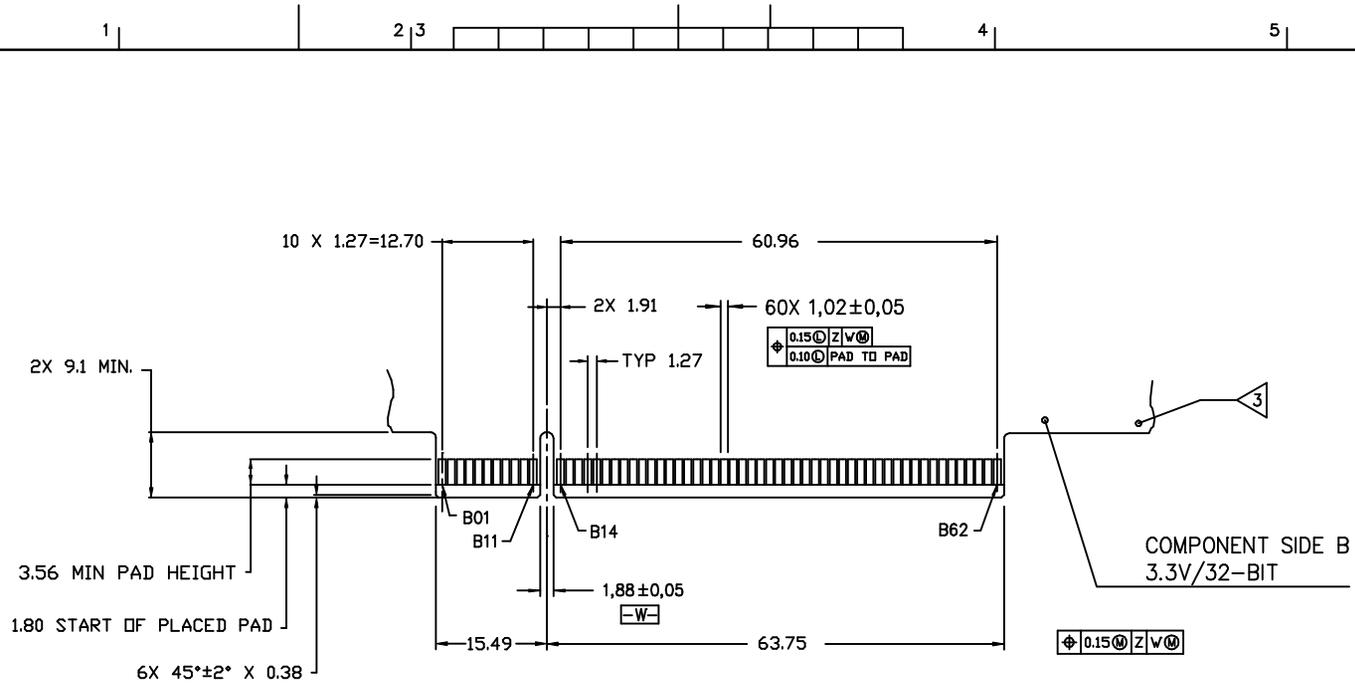
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FCI

mat'l. code		tolerances unless otherwise specified		CUSTOMER COPY		FCI www.fciconnect.com	
ltr	scn no	dr	date	.X ± 0.30	projection	title	
A	T20298	J H	1/16/03	.XX ± 0.20		PCI CARD EDGE CONNECTOR	
				.XXX ± 0.10		CEE2X60S-V_Z52NA	
				ANGLES ±2°	MM	product family	code
dr	JASON HSU	1/16/03				PCI	TWN
enr	JASON HSU	1/16/03				size	dwg no
chr	STERLING LIN	1/16/03		scale		10016454	1 of 3
appd	JAMES HSU	1/16/03		1 : 1	A3		
sheet index	revision sheet	A	A	1	2	3	

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TYPICAL CARD EDGE PROFILE

mat'l. code		tolerances unless otherwise specified		CUSTOMER COPY		 www.fciconnect.com	
ltr	ecn no	dr	date	linear	.x ± 0.30	projection	title
A					.XX ± 0.20	 MM	PCI CARD EDGE CONNECTOR CEE2X60S-V_Z52NA
					.XXX ± 0.10		product family PCI
				angles	ANGLES ± 2°	scale	size dwg no
				dr	JASON HSU 1/16/03	1 : 1	A3 10016454
				enr	JASON HSU 1/16/03		
				chr	STERLING LIN 1/16/03		
				appd	JAMES HSU 1/16/03		
sheet index	revision sheet						code
							TWN
							sheet 2 of 3

NOTES UNLESS OTHERWISE SPECIFIED.

1. INTERPRET THIS DRAWING IN ACCORDANCE WITH ANSI Y14.5M-1982
2. SEE SHEET 1, 2 FOR RECOMMENDED MATING DAUGHTERCARD AND MOTHERBOARD LAYOUTS.
3. MATING DAUGHTERBOARD MATERIAL:
 PC BOARD FR-4 WITH 1 OZ[28.35 GRAMS] MIN. COPPER PADS
 PAD PLATING 30 MICROINCHES [0.76 MICRONS] MIN. GOLD PER MIL-G-45204. TYPE 1 CLASS 1, GRADE C OVER 100 MICROINCHES[2.54 MICRONS] MIN. NICKEL PER QQ-N-290

MATERIALS

BODY - POLYESTER PBT. RATED UL 94V-2, COLOR WHITE.
 CONTACTS - COPPER ALLOY.

FINISH CONTACTS

Z52 PLATING GOLD FLASH OVER NICKEL UNDERPLATE IN CRITICAL CONTACT AREA AND 100 MICROINCHES (2.54 MICRONS) SOLDER OVER NICKEL UNDERPLATE ON SOLDER TAILS.

PERFORMANCE CHARACTERISTICS :

CONTACT RESISTANCE :MIL-STD-1344. METHOD 3002.1. 30 MILLIOHMS. MAX. INITIAL 10 MILLIOHMS MAX. INCREASE THROUGH TESTING. (LOW SIGNAL LEVEL)

CURRENT RATING : 1 AMPERE. 86°F(30°) RISE ABOVE AMBIENT.

CONTACT NORMAL FORCE : 1.76 OZ FORCE (0.49 NEWTONS) MINIMUM END OF LIFE.

DURABILITY : 50 MATING CYCLES WITHOUT PHYSICAL DAMAGE . OR EXCEEDING LOW LEVEL CONTACT RESISTANCE REQUIREMENT

WHEN MATED WITH RECOMMENDED CARD EDGE.

INSULATION RESISTANCE : MIL-STD-202. METHOD 302. CONDITION B. 1000 MEGOHMS MINIMUM.

OPERATING TEMPERATURE : -40°F TO 221°F(-40°C TO 105°C)

THERMAL SHOCK : MIL-STD-202. METHOD 1003.1 -67°F TO 185°F[155°C TO 85°C] 5 CYCLES.

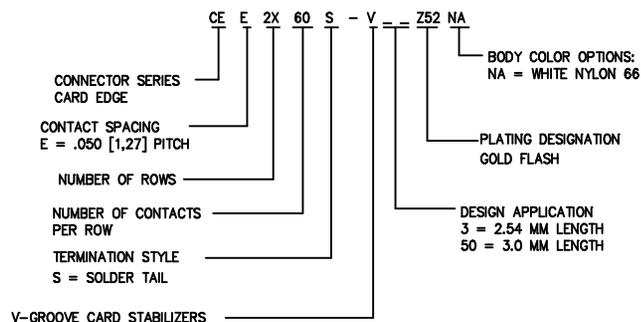
CAPACITANCE : 2 PICOFARADS MAXIMUM AT 1 MEGAHERTZ

MATING FORCE :MIL-STD-1344. METHOD 2013.1. 6 OZ.(1.67 NEWTONS) MAX. AVERAGE PER OPPOSING PAIR USING STEEL GAUGE PER MIL-STD C--21097 EXCEPT 1.57MM THICK WITH 20° LEAD-IN CHAMFER ANGLE.

CONNECTOR IS COMPATIBLE WITH WAVE SOLDERING AND VAPOR PHASE SOLDERING TECHNIQUES.

CONNECTOR INSTALLATION FORCE 15 LBS [66.76 NEWTONS] MAX.

CATALOG NUMBER DESCRIPTION



mat'l. code		tolerances unless otherwise specified		CUSTOMER COPY		 www.fciconnect.com	
ltr	ecn no	dr	date	linear	.XX ± 0.20	projection	title
A					.XXX ± 0.10		PCI CARD EDGE CONNECTOR CEE2X60S-V_Z52NA
				angles	ANGLES ±2°		product family PCI
				dr	JASON HSU 1/16/03*	←	code
				enr	JASON HSU 1/16/03*	→	TWN
				chr	STERLING LIN 1/16/03*	scale	size
				appd	JAMES HSU 1/16/03*	1 : 1	dwg no
sheet	revision					A3	10016454
index	sheet						code
							TWN
							sheet
							3 of 3